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3 B24

Docket No. 45475-00028  
99-44653

#11  
Response  
Sub Spec  
8-1-02  
DRJ

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:  
Sung Sik Jang

Serial No.: 09/687493

Examiner: Alexander Williams

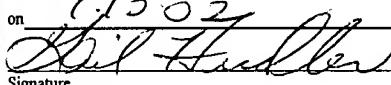
Confirmation No.

Filed: October 13, 2000

Group Art Unit: 2826

For: SEMICONDUCTOR PACKAGE HAVING IMPROVED ADHESIVENESS AND  
GROUND BONDING

Assistant Commissioner for Patents  
Washington, DC 20231

CERTIFICATE OF MAILING	
I hereby certify that this correspondence is being deposited postage paid with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, Washington, DC 20231	
on	7-12-02
	
Signature	

Dear Sir:

**AMENDMENT**

Responsive to the Office Action dated January 24, 2002, please amend the above-  
identified application for patent as follows:

07/19/2002 GWORDOF1 0000002 09687493  
01 FC:117  
920.00 OP

**IN THE SPECIFICATION**

Please substitute the specification as attached hereto in **EXHIBIT A**. A marked-up  
version of the substitute specification is attached as **EXHIBIT B** to this Amendment. The  
substitute specification is submitted herewith under 37 CFR 1.121 and 1.125. No new matter has  
been added.